

(0.635 mm) .025"

QMS SERIES

RUGGED GROUND PLANE HEADER

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?QMS

Insulator Material:

Liquid Crystal Polymer

Terminal & Ground

Plane Material:

Phosphor Bronze

Plating:

Au over 50 μ " (1.27 μ m) Ni

(Tin on Ground Plane Tail)

Current Rating:

Contact:

2.6 A per pin

(2 pins powered)

Ground Plane:

15.7 A per ground plane

(1 ground plane powered)

Operating Temp:

-55 °C to +125 °C

Voltage Rating:

300 VAC mated with QFS

RoHS Compliant:

Yes

Board Mates:

QFS

Cable Mates:

6QCD

Standoffs:

SO, JSOM

ALSO AVAILABLE (MOQ Required)

- Other platings
- Guide Posts
- Without PCB Alignment Pins (05.75 and 06.75 only)
- Hot Pluggable
- 64 (-DP) and 104 positions per row

HIGH-SPEED CHANNEL PERFORMANCE

QMS-DP/QFS-DP @ 10 mm Mated Stack Height

Rating based on Samtec reference channel.
For full SI performance data visit Samtec.com
or contact SIG@samtec.com

25
Gbps

Integral metal plane
for power or ground

Increased
insertion depth for
rugged applications

(1.60 mm)
.063"
NOMINAL
WIPE

POWER/SIGNAL APPLICATION

Compatible with
UMPT/UMPS for flexible
two-piece power/signal solutions

PROCESSING

Lead-Free Solderable:

Yes

SMT Lead Coplanarity:

(0.10 mm) .004" max (026-052)

(0.15 mm) .006" max (078)*

*(.004" stencil solution

may be available; contact

IPG@samtec.com)

Board Stacking:

For applications requiring more
than two connectors per board,
contact ipg@samtec.com

RECOGNITIONS

For complete scope of
recognitions see
www.samtec.com/quality



STANDARDS

- SUMIT™
- PCI/104-Express™
- PCI/104-Express™ OneBank

Visit www.samtec.com/standards
for more information.

QMS	PINS PER ROW NO. OF PAIRS	LEAD STYLE	PLATING OPTION	TYPE	A	OTHER OPTION
	-026, -052, -078 (52 total pins per bank = -D) -016, -032, -048 (16 pairs per bank = -D-DP) (-078 & -048 Not available with -09.75 lead style)	Specify LEAD STYLE from chart	-L (-05.75 and -06.75 lead style only) = 10 μ " (0.25 μ m) Gold on Signal Pins and Ground Plane (Tin on Signal Pin tails, and Ground Plane tails) -SL (-09.75 lead style only) = 10 μ " (0.25 μ m) Gold on Signal Pins and Ground Plane (Tin on Signal Pin tails, and Ground Plane tails)	-D = Single-Ended -D-DP = Differential Pair		-K = (5.50 mm) .217" DIA Polyimide film Pick & Place Pad

-D

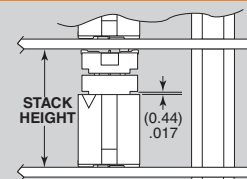
-D-DP

MATED HEIGHT*			
LEAD STYLE	A	QFS LEAD STYLE	
		-04.25	-06.25
-05.75	(5.38) .212	10 mm	12 mm
-06.75	(6.35) .250	11 mm	13 mm
-09.75	(9.35) .368	14 mm	16 mm

*Processing conditions will affect mated height.
See SO Series for board space tolerances.

INDUSTRY STANDARD	INTERCONNECTS			
	TERMINAL	SOCKET	BANKS	STACK HEIGHT
SUMIT™	ASP-129637-01	ASP-129646-01	1	15.24 mm
PCI/104-Express™	ASP-129637-03	ASP-129646-03	3	15.24 mm
PCI/104-Express™	ASP-129637-13	ASP-129646-22	1	15.24 mm
PCI/104-Express™	ASP-142781-01	ASP-129646-01	1	22 mm
PCI/104-Express™	ASP-142781-02	ASP-129646-02	2	22 mm
PCI/104-Express™	ASP-142781-03	ASP-129646-03	3	22 mm

APPLICATION



Requires Standoff
SO-1524-03-01-01-L or
JSOM-1524-02 for 15.24 mm
or SO-2215-02-01-01-L for 22 mm
board spacing. Connectors designed
to not fully seat when mated.